

## ETHE COMMISSIONER OF PATENTS AND TRADEMARKS

Washington, D.C. 20231

Dear Sir:

Transmitted herewith for filing is the patent application of

Inventor(s):

Harry Chan and Elio Moy

Title:

PIPE EXTRUSION DIE FOR MULTI-LAYER PIPE

## Enclosed are:

- (X) Disclosure
- (X) Claims
- (X) Abstract
- (X) Formal drawings (4 sheets)
- (X) Declaration/Power of Attorney
- ( ) \_\_\_\_ Assignment(s)
- ( ) Certified copy of the priority document(s)
- ( ) Cheque in the amount of \$

to be applied as follows:

Filing fee

\$ 661.00

## THE FILING FEE HAS BEEN CALCULATED AS SHOWN BELOW:

	No. Filed	No. Extra
Basic Fee		
Total Claims	54-20	34
Indep. Claims	3- 3	
( )Multiple dependent claims presented		

	Small Entity	
RATE	FEE	
	\$355.00	
x 9=	\$306.00	
x 40=	\$	
+135=	\$	
TOTAL	\$661.00	

		Large Entity
<u>OR</u>	RATE	FEE
<u>OR</u>	•	\$710.00
<u>OR</u>	x 18=	\$
<u>OR</u>	x 80=	\$
<u>OR</u>	+270=	\$
OR	TOTAL	\$

Our Ref: <u>1142-2/AMF</u>

April 5, 2001

Date:

(X) Applicant claims small entity status.

Please direct all correspondence and telephone inquiries to the undersigned at the address below.

Respectfully submitted,

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